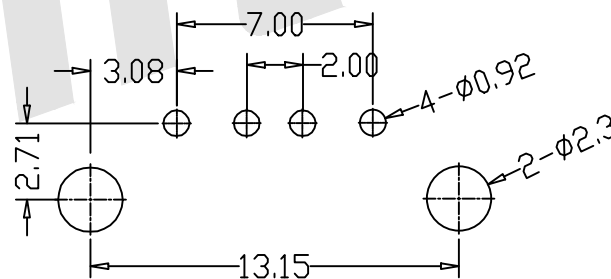
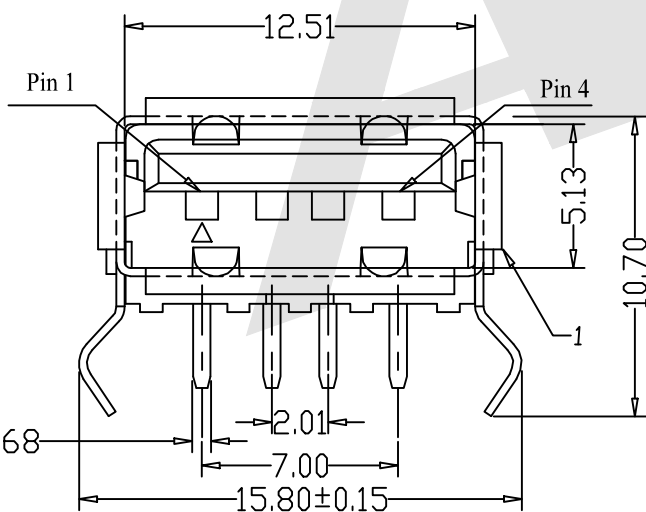
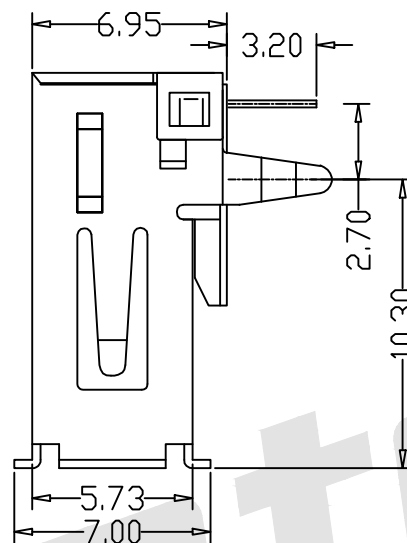
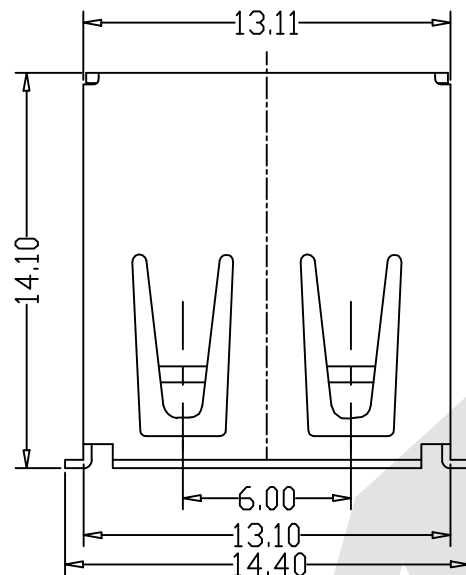


HSF



RECOMMENDED PCB LAYOUT

Specifications:
 Current Rating: 1.5A Max
 Contact Resistance: 30 milliohms MAX
 Dielectric Withstanding Voltage: 500V AC AT Sea Level
 Insulation Resistance: 1000 Megohms MIN
 Housing: Temperature Thermoplastics, PBT UL 94V-0
 Contact: Copper Alloy T=0.25mm Plated Gold in Mating Area; Tin On Solder Tails
 Shell: Iron T=0.30mm Nickel/Plating

Ordering Code:

UAFR01 - X - X - X - X - X - X
 ① ② ③ ④ ⑤ ⑥ ⑦

- ① Series No:
- ② Shell Material:
B:Brass I:Iron S:stainless steel
- ③ Insulator Material:
P:PBT+30%GF L:LCP
- ④ Contact Material:
B:Brass P:phosphor copper
- ⑤ Contact Plating:
G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold
- ⑥ Color Insulator:
A:White B:Black
- ⑦ Packing:
A:Tray B:Bag C:Tube D:Tape & Reel

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
 DRAW Lv Xun Hua DATE 17/06/2019
 CHECK BobYang DATE 17/06/2019



Antenk® ANTENK ELECTRONICS CO., LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE:
 USB A Type Receptacle Angle DIP

DRAWING NO: UAFR01-XXXXXX

PRODUCT NO: UAFR01-XXXXXX

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		